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December 2014

FDPF041N06BL1

N-Channel PowerTrench[®] MOSFET 60 V, 77 A, 4.1 m Ω

Features

- $R_{DS(on)} = 3.5 \text{ m}\Omega$ (Typ.) @ $V_{GS} = 10 \text{ V}$, $I_D = 77 \text{ A}$
- Low FOM R_{DS(on)}*Q_G
- Low Reverse Recovery Charge, Q_{rr}
- Soft Reverse Recovery Body Diode
- Enables Highly Efficiency in Synchronous Rectification
- · Fast Switching Speed
- 100% UIL Tested
- · RoHS Compliant

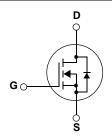
Description

This N-Channel MOSFET is produced using Fairchild Semiconductor[®]'s advanced PowerTrench[®] process that has been tailored to minimize the on-state resistance while maintaining superior switching performance.

Applications

- Synchronous Rectification for ATX / Server / Telecom PSU
- Battery Protection Circuit
- Motor Drives and Uninterruptible Power Supplies
- Renewable System





MOSFET Maximum Ratings T_C = 25°C unless otherwise noted*

Symbol		Parameter		FDPF041N06BL1	Unit
V _{DSS}	Drain to Source Voltage			60	V
V _{GSS}	Gate to Source Voltage			±20	V
I _D	Drain Current	- Continuous (T _C = 25°C, Silicon Li	mited)	77	А
	Drain Current	- Continuous (T _C = 100°C, Silicon I	_imited)	55	_ A
I _{DM}	Drain Current	- Pulsed	(Note 1)	308	Α
E _{AS}	Single Pulsed Avalanche Er	ergy	(Note 2)	365	mJ
dv/dt	Peak Diode Recovery dv/dt		(Note 3)	6.0	V/ns
D	Danier Diagination	$(T_C = 25^{\circ}C)$		44.1	W
P_{D}	Power Dissipation	- Derate above 25°C	- Derate above 25°C		W/°C
T _J , T _{STG}	Operating and Storage Tem	perature Range		-55 to +175	οС
T _L	Maximum Lead Temperature 1/8" from Case for 5 Second	• • •		300	°C

Thermal Characteristics

Symbol	Parameter FDPF04		Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max	3.4	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max	62.5	-0/00

Package Marking and Ordering Information

Device Marking	Device	Package	Packaging Type	Quantity
FDPF041N06BL1	FDPF041N06BL1	TO-220F	Tube	50

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	eteristics					
BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	60	-	-	V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I _D = 250μA, Referenced to 25°C	-	0.03	-	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 48V, V_{GS} = 0V$	-	-	1	μΑ
I_{GSS}	Gate to Body Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	±100	nA

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	2	-	4	V
R _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 10V, I_{D} = 77A$	•	3.5	4.1	mΩ
9 _{FS}	Forward Transconductance	$V_{DS} = 10V, I_{D} = 77A$	-	125	-	S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 00V V 0V	-	4280	5690	pF
C _{oss}	Output Capacitance	$V_{DS} = 30V, V_{GS} = 0V$ f = 1MHz	-	1050	1400	pF
C _{rss}	Reverse Transfer Capacitance		-	23	-	pF
C _{oss(er)}	Energy Related Output Capacitance	$V_{DS} = 30V, V_{GS} = 0V$	-	1787	-	pF
Q _{g(tot)}	Total Gate Charge at 10V		-	53	69	nC
Q_{gs}	Gate to Source Gate Charge	$V_{DS} = 30V, I_D = 100A$ $V_{GS} = 10V$	-	23	-	nC
Q _{gd}	Gate to Drain "Miller" Charge		-	8	-	nC
V _{plateau}	Gate Plateau Volatge	(Note 4	-	5.7	-	V
Q _{sync}	Total Gate Charge Sync.	$V_{DS} = 0V, I_D = 50A$ (Note 5)	-	48.6	-	nC
Q _{oss}	Output Charge	$V_{DS} = 30V, V_{GS} = 0V$	-	63.8	-	nC

Switching Characteristics

t _{d(on)}	Turn-On Delay Time			-	29	68	ns
t _r	Turn-On Rise Time	$V_{DD} = 30V, I_{D} = 100A$		-	22	54	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10V$, $R_{GEN} = 4.7\Omega$		-	38	86	ns
t _f	Turn-Off Fall Time		(Note 4)	-	11	32	ns
ESR	Equivalent Series Resistance (G-S)	f = 1MHz		-	0.8	-	Ω

Drain-Source Diode Characteristics

I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	77	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	308	Α
V_{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _{SD} = 77A	-	-	1.25	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0V, I _{SD} = 100A	-	65	-	ns
Q _{rr}	Reverse Recovery Charge	$dI_F/dt = 100A/\mu s$	-	63	-	nC

Notes:

- Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. L = 3mH, I_{AS} = 15.6A, Starting T_J = 25°C
- 3. $I_{SD} \leq$ 100A, di/dt \leq 200A/ μ s, $V_{DD} \leq$ BV $_{DSS}$, Starting T_J = 25°C
- 4. Essentially Independent of Operating Temperature Typical Characteristics
- 5. See the test circuit in page 8

Typical Performance Characteristics

Figure 1. On-Region Characteristics

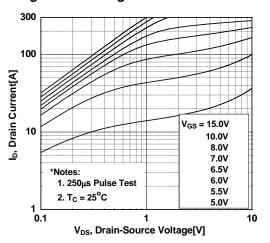


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

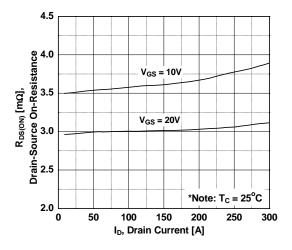


Figure 5. Capacitance Characteristics

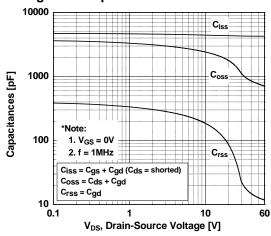


Figure 2. Transfer Characteristics

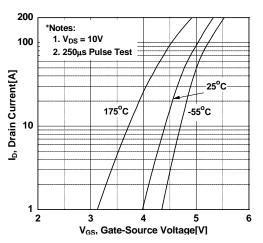


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

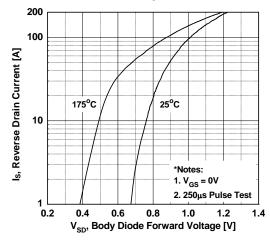
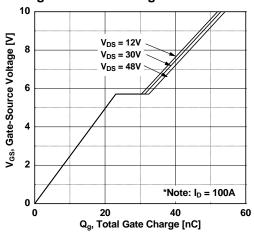


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

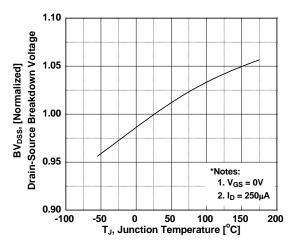


Figure 9. Maximum Safe Operating Area vs. Case Temperature

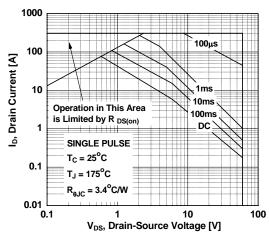


Figure 11. Eoss vs. Drain to Source Voltage

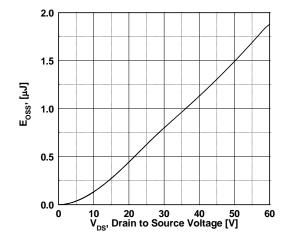


Figure 8. On-Resistance Variation vs. Temperature

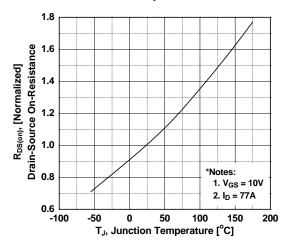


Figure 10. Maximum Drain Current

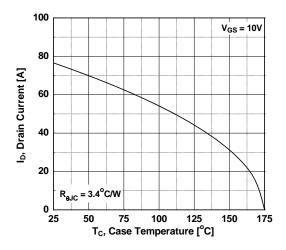
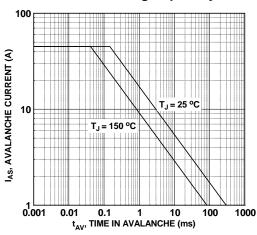
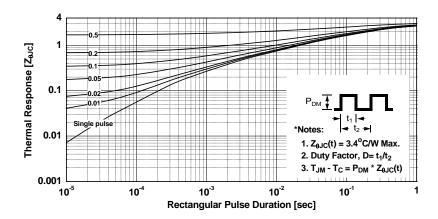


Figure 12. Unclamped Inductive Switching Capability

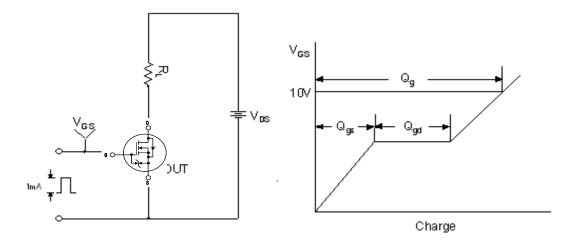


Typical Performance Characteristics (Continued)

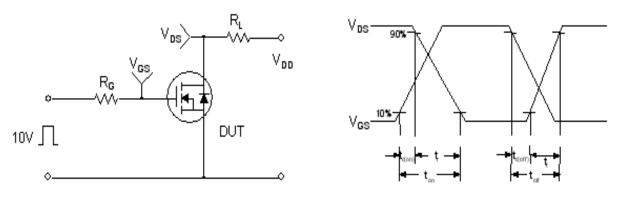




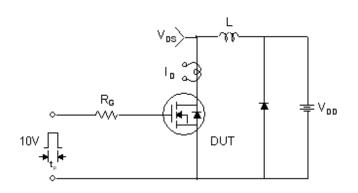
Gate Charge Test Circuit & Waveform

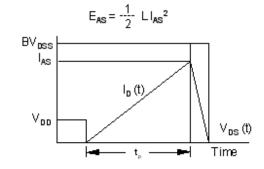


Resistive Switching Test Circuit & Waveforms

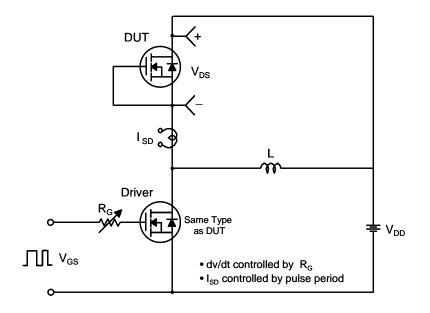


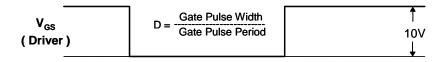
Unclamped Inductive Switching Test Circuit & Waveforms

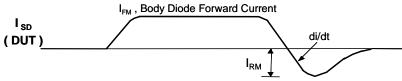




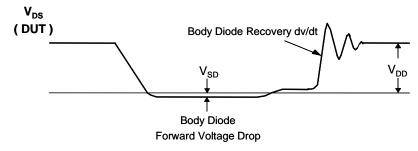
Peak Diode Recovery dv/dt Test Circuit & Waveforms



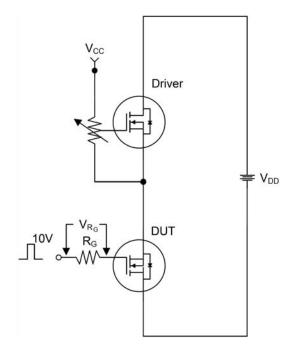


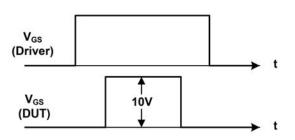


Body Diode Reverse Current

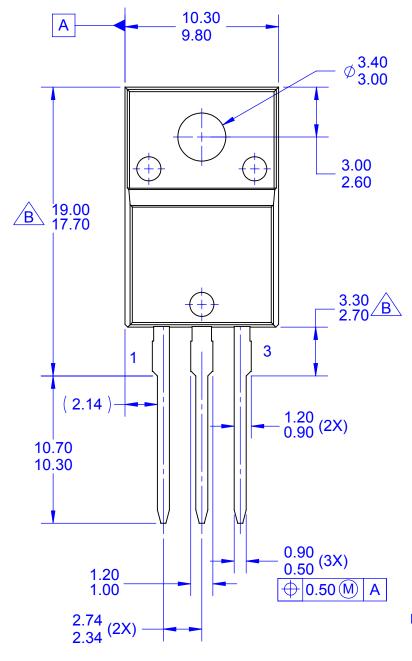


Total Gate Charge Qsync. Test Circuit & Waveforms

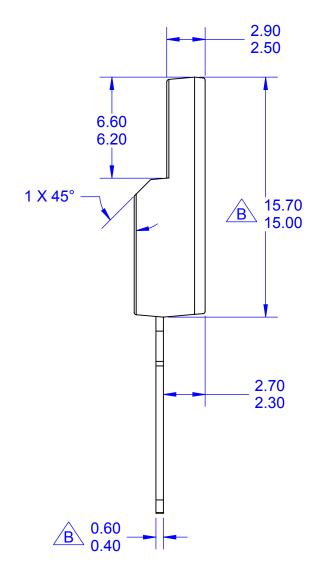




$$Qsync = \frac{1}{R_G} \cdot \int V_{R_G}(t) dt$$







NOTES:

- A. EXCEPT WHERE NOTED CONFORMS TO
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- D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS. E. DIMENSION AND TOLERANCE AS PER ASME
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